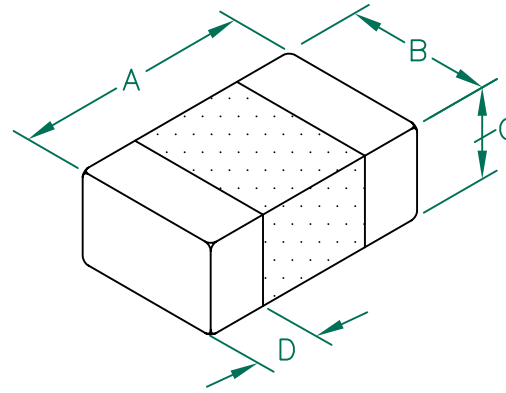


# LI0805H750R-10

**UNCONTROLLED DOCUMENT**

## PHYSICAL DIMENSIONS:

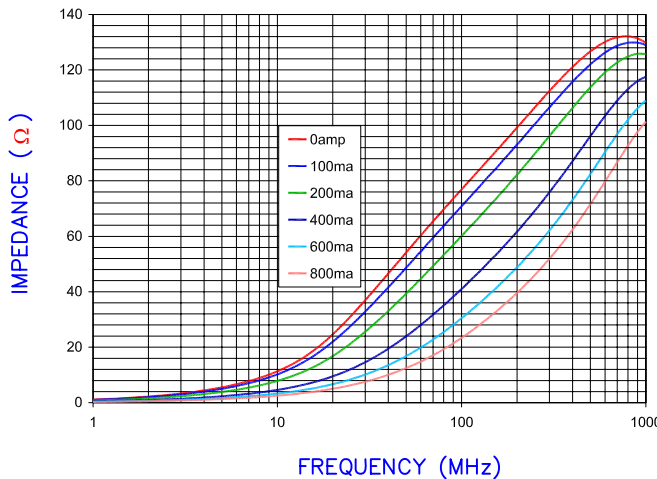
A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]



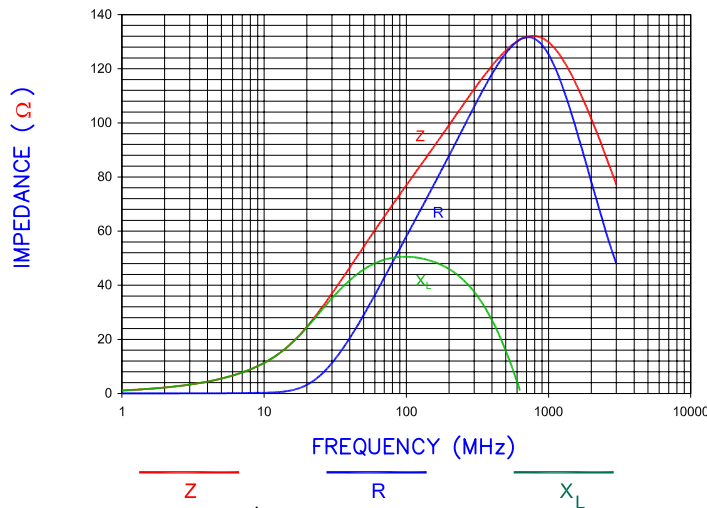
## ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz ( $\Omega$ )	DCR ( $\Omega$ )	Rated Current
Nominal	75		
Minimum	56		
Maximum	94	0.15	800 mA

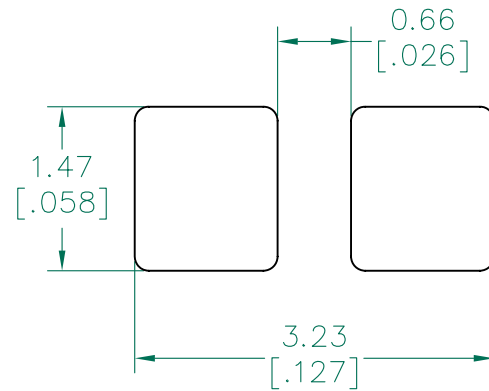
Z vs FREQUENCY  
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)  
|Z|, R, AND X vs. FREQUENCY

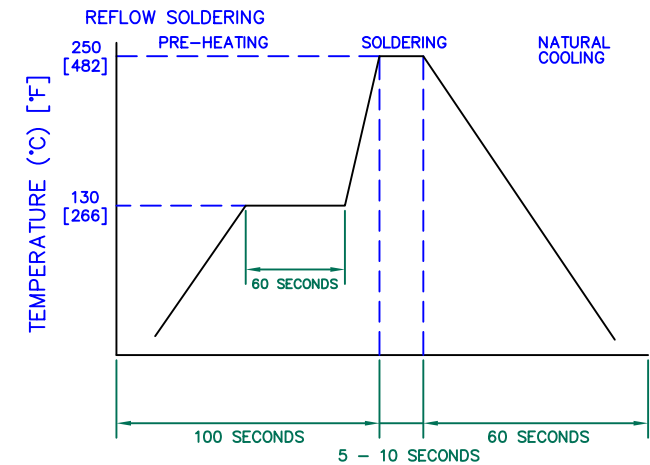


## LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension.)

## RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.				<b>Laird TECHNOLOGIES</b>	
PROJECT/PART NUMBER:				REV	PART TYPE:	DRAWN BY:			
LI0805H750R-10				C	CO-FIRE	TMB			
C	CHANGE TO PAPER TAPE	03/04/10	JUN	DATE:	04/05/04	SCALE:	NTS	SHEET: 2 of 2	
B	UPDATE COMPANY LOGO ADD ROHS SYM	07/21/08	JRK	CAD #	LI0805H750R-10-C	TOOL #	-		
A	ORIGINAL DRAFT	04/05/04	TMB	REV	DESCRIPTION	DATE	INT		